

MOSFET – Power, N-Channel, SUPERFET® III, FAST

650 V, 64 mΩ, 40 A

NTMT064N65S3H

Description

SUPERFET III MOSFET is onsemi's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SUPERFET III FAST MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency.

The Power88 package is an ultra-slim surface-mount package (1 mm high) with a low profile and small footprint (8 x 8 mm²). SUPERFET III MOSFET in a Power88 package offers excellent switching performance due to lower parasitic source inductance and separated power and drive sources. Power88 offers Moisture Sensitivity Level 1 (MSL 1).

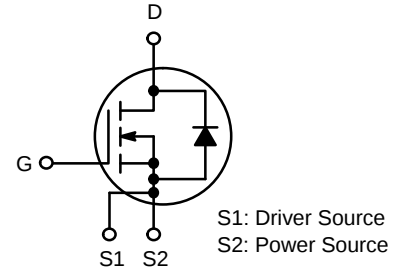
Features

- 700 V @ T_J = 150 °C
- Typ. R_{DS(on)} = 52 mΩ
- Ultra Low Gate Charge (Typ. Q_g = 82 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 750 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

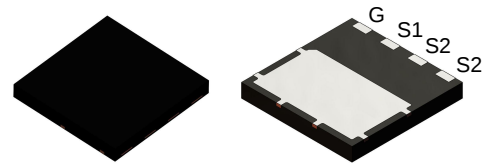
Applications

- Telecom / Server Power Supplies
- Industrial Power Supplies
- UPS / Solar

V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	64 mΩ @ 10 V	40 A

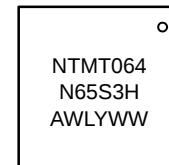


POWER MOSFET



TDFN4 8X8 2P
CASE 520AB

MARKING DIAGRAM



NTMT064N65S3H = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

NTMT064N65S3H

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, Unless otherwise noted)

Symbol	Parameter		Value	Unit
V _{DSS}	Drain to Source Voltage		650	V
V _{GSS}	Gate to Source Voltage	– DC	±30	V
		– AC (f > 1 Hz)	±30	
I _D	Drain Current	– Continuous (T _C = 25 °C)	40	A
		– Continuous (T _C = 100 °C)	25	
I _{DM}	Drain Current	– Pulsed (Note 1)	112	A
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		422	mJ
I _{AS}	Avalanche Current (Note 2)		6.5	A
E _{AR}	Repetitive Avalanche Energy (Note 1)		2.60	mJ
dv/dt	MOSFET dv/dt		120	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	
P _D	Power Dissipation	(T _C = 25 °C)	260	W
		– Derate Above 25 °C	2.08	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		–55 to +150	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. I_{AS} = 6.5 A, R_G = 25 Ω, starting T_J = 25 °C.

3. I_{SD} ≤ 20 A, di/dt ≤ 200 A/μs, V_{DD} ≤ 400 V, starting T_J = 25 °C.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R _{θJC}	Thermal Resistance, Junction to Case, Max.	0.48	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient, Max. (Note 4)	45	

4. Device on 1 in² pad 2 oz copper pad on 1.5 x 1.5 in. board of FR-4 material.

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Reel Size	Tape Width	Shipping Quantity [†]
NTMT064N65S3H	NTMT064N65S3H	TDFN4	13"	13.3 mm	3000 Units / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).



NTMT064N65S3H

ELECTRICAL CHARACTERISTICS ($T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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OFF CHARACTERISTICS

BV _{DSS}	Drain to Source Breakdown Voltage	V _{GS} = 0 V, I _D = 1 mA, T _J = 25 °C	650			V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150 °C	700			V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25 °C		0.63		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V			10	μA
		V _{DS} = 520 V, T _C = 125 °C		3.2		
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V			±100	nA

ON CHARACTERISTICS

V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 3.9 mA	2.4		4.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 20 A		52	64	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 20 A		44		S

DYNAMIC CHARACTERISTICS

C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 250 kHz		3745		pF
C _{oss}	Output Capacitance			58		pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		750		pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		100		pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 400 V, I _D = 20 A, V _{GS} = 10 V (Note 5)		82		nC
Q _{gs}	Gate to Source Gate Charge			20		nC
Q _{gd}	Gate to Drain "Miller" Charge			23		nC
ESR	Equivalent Series Resistance	f = 1 MHz		0.7		Ω

SWITCHING CHARACTERISTICS

t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 20 A, V _{GS} = 10 V, R _g = 4.7 Ω (Note 5)		29		ns
t _r	Turn-On Rise Time			16		ns
t _{d(off)}	Turn-Off Delay Time			85		ns
t _f	Turn-Off Fall Time			3.1		ns

SOURCE-DRAIN DIODE CHARACTERISTICS

I _S	Maximum Continuous Source to Drain Diode Forward Current			40		A
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current			112		A
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 20 A			1.2	V
t _{rr}	Reverse Recovery Time	V _{DD} = 400 V, I _{SD} = 20 A, di/dt = 100 A/μs		367		ns
Q _{rr}	Reverse Recovery Charge			6.3		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Essentially independent of operating temperature typical characteristics.



TYPICAL CHARACTERISTICS

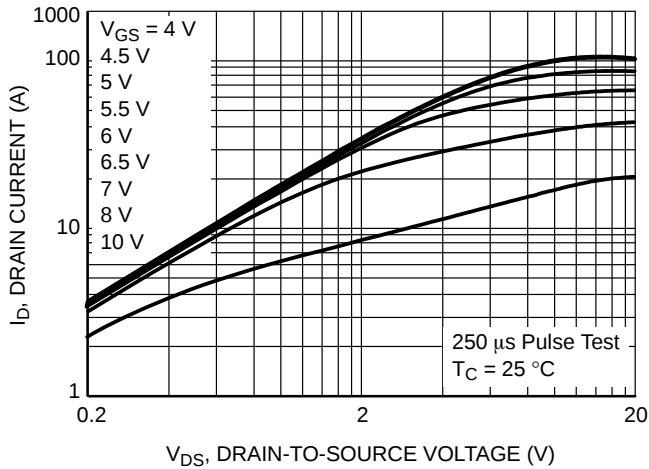


Figure 1. On-Region Characteristics

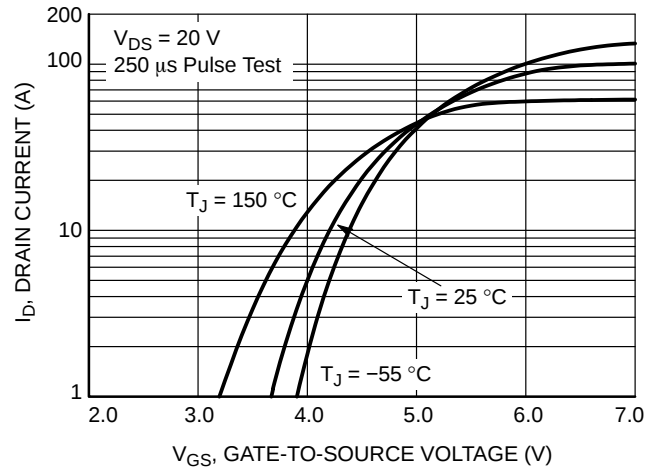


Figure 2. Transfer Characteristics

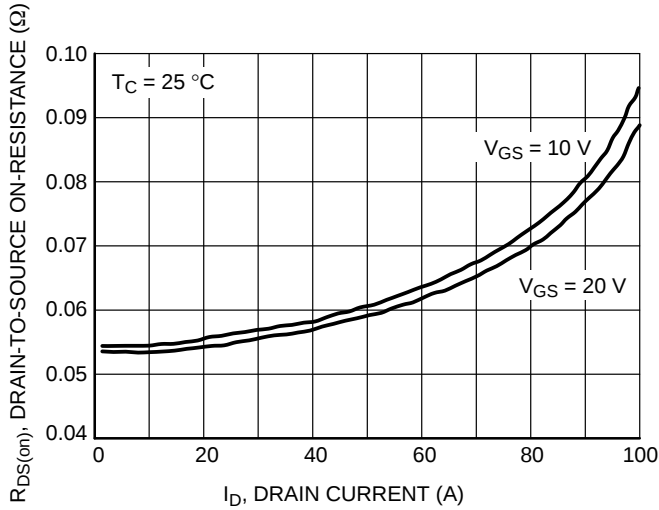


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

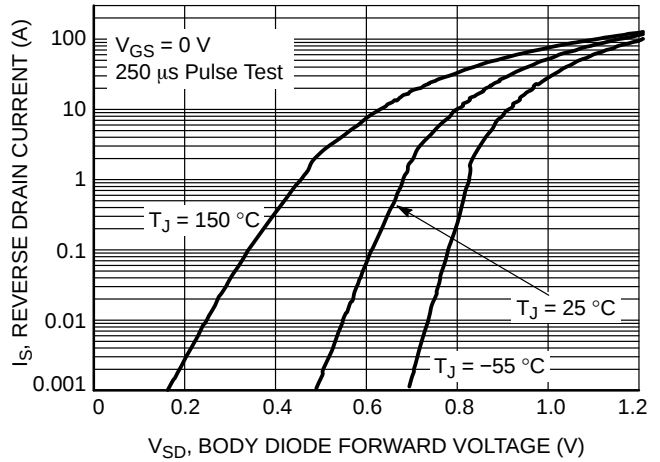


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

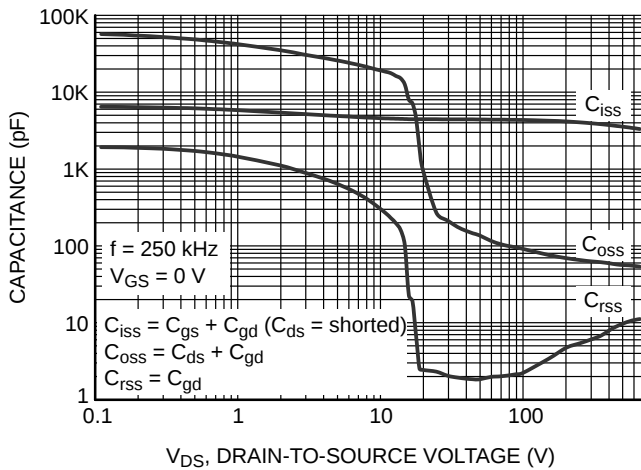


Figure 5. Capacitance Characteristics

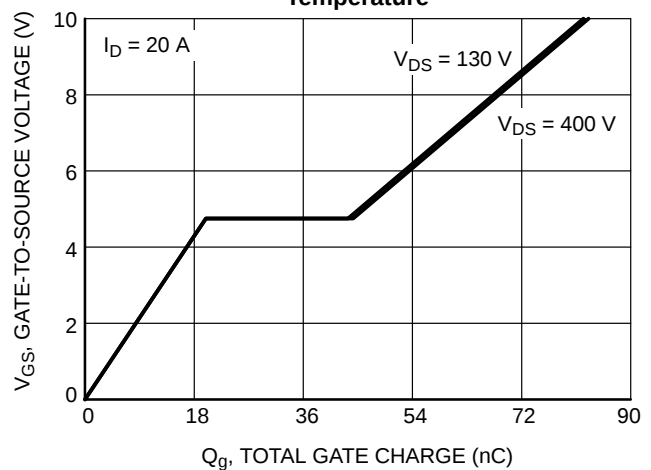


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS

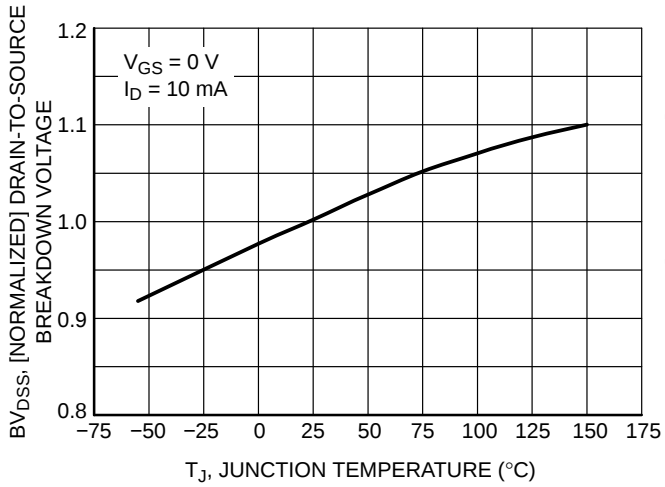


Figure 7. Breakdown Voltage Variation vs. Temperature

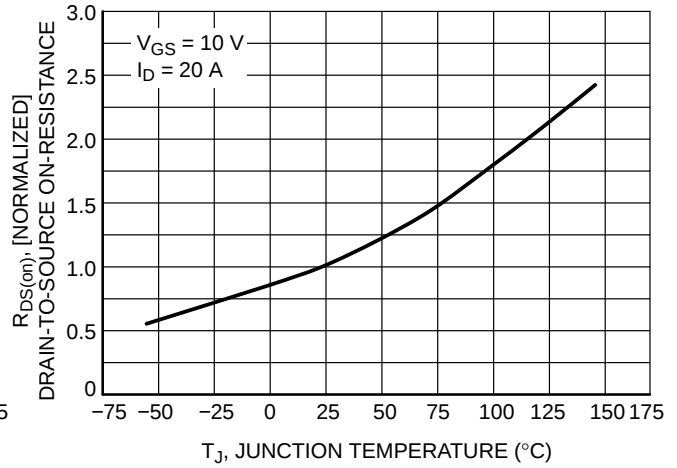


Figure 8. On-Resistance Variation vs. Temperature

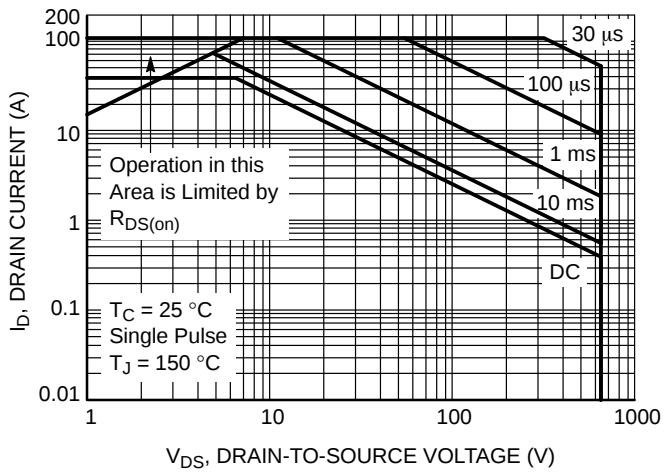


Figure 9. Maximum Safe Operating Area

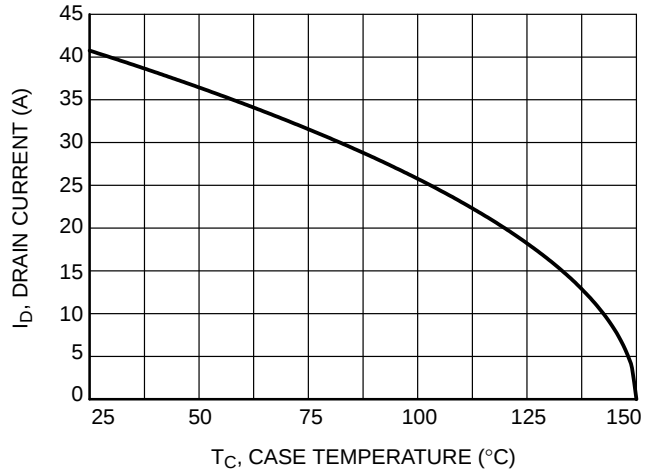


Figure 10. Maximum Drain Current vs. Case Temperature

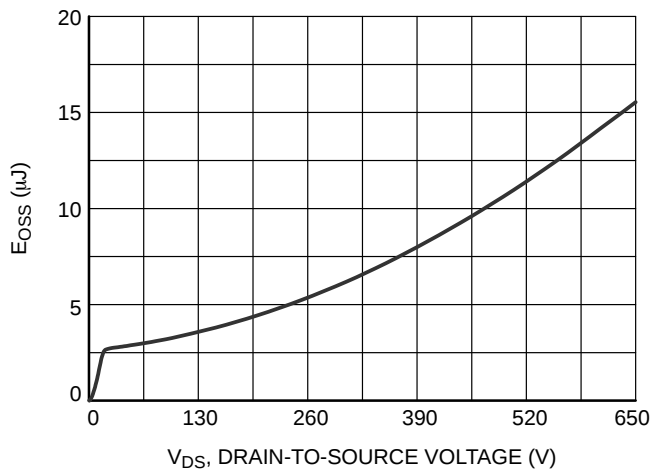


Figure 11. E_{OSS} vs. Drain-to-Source Voltage

TYPICAL CHARACTERISTICS

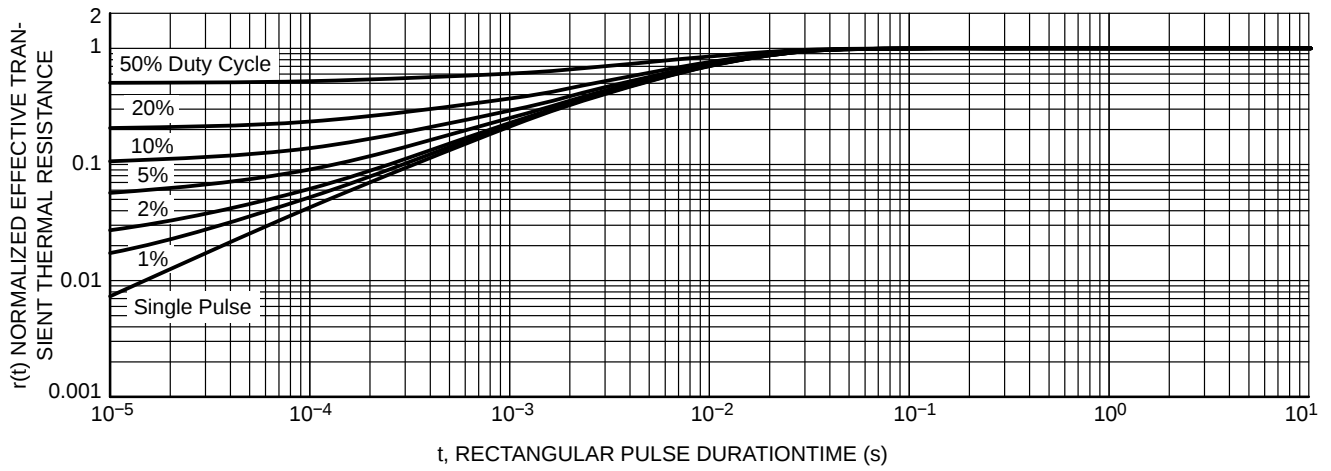


Figure 12. Transient Thermal Response Curve

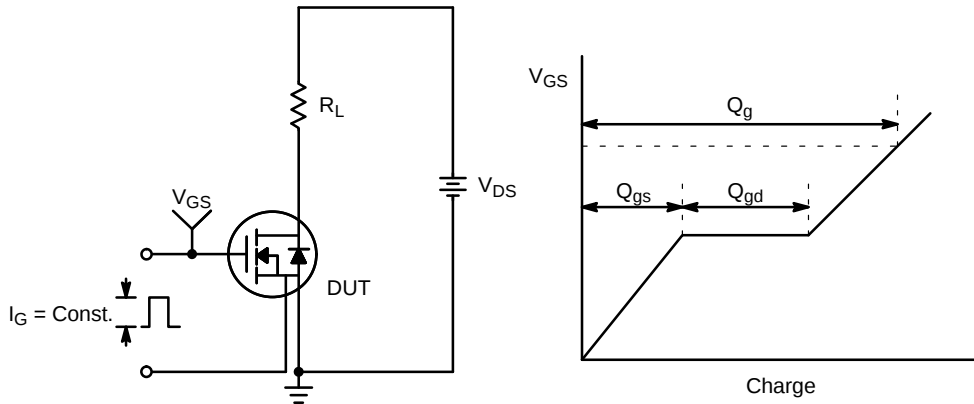


Figure 13. Gate Charge Test Circuit & Waveform

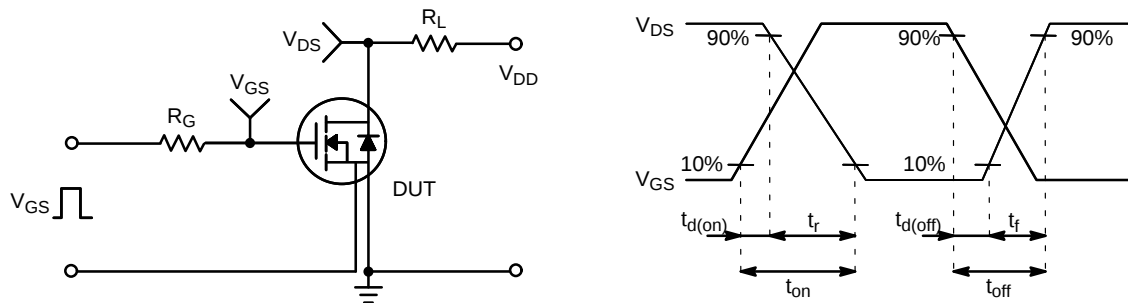


Figure 14. Resistive Switching Test Circuit & Waveforms

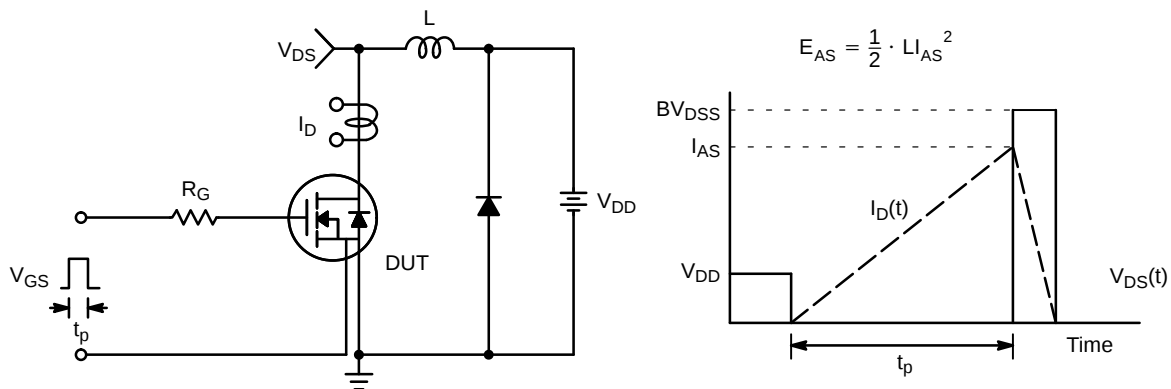


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

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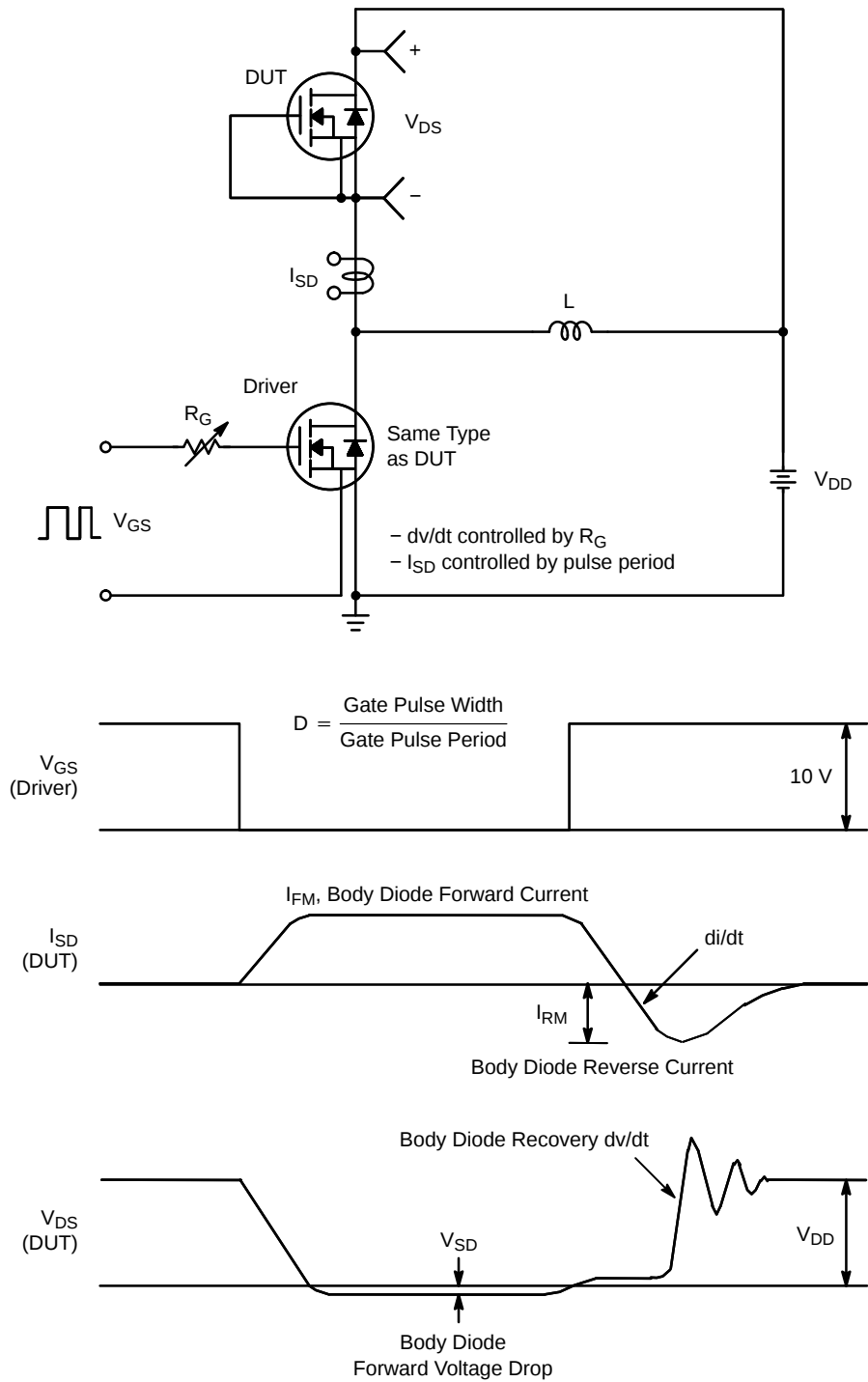


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

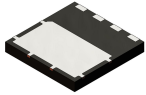
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REVISION HISTORY

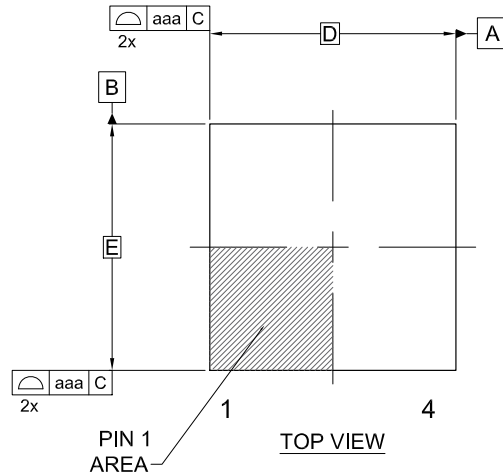
Revision	Description of Changes	Date
2	Rebranded the document to onsemi format.	1/16/2026

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

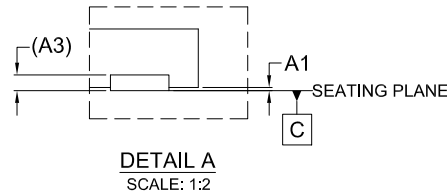



TDFN4 8.00x8.00x1.00, 2.00P
CASE 520AB
ISSUE A

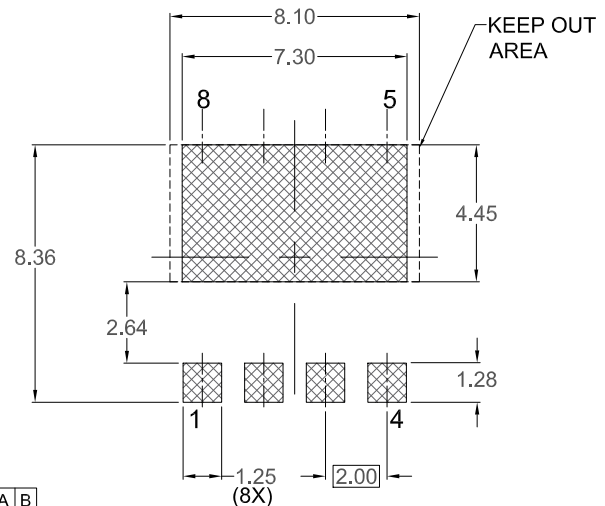
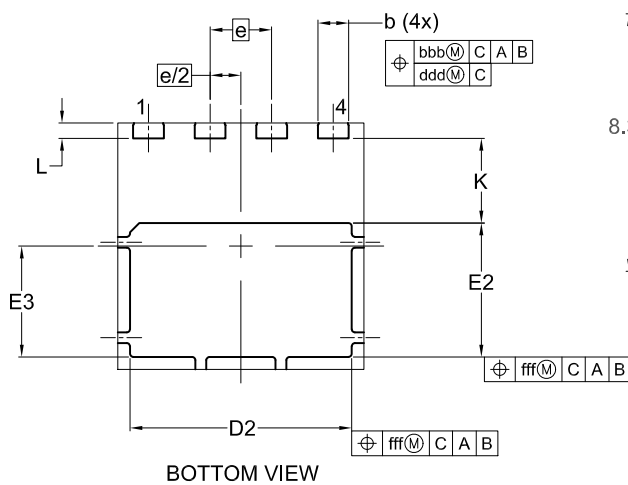
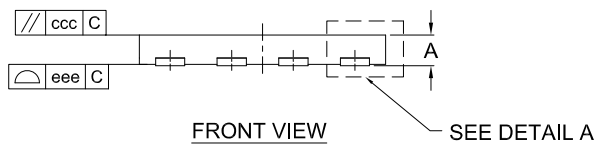
DATE 07 JUN 2024


NOTES:

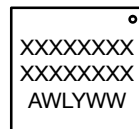
- A) DIMENSIONS AND TOLERANCING CONFIRM TO ASME Y14.5-2018.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
D) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	---	0.05
A3	0.20 REF		
b	0.90	1.00	1.10
D	8.00 BSC		
D2	7.10	7.20	7.30
E	8.00 BSC		
E2	4.25	4.35	4.45
E3	3.50	3.60	3.70
e	2.00 BSC		
e/2	1.00 BSC		
K	2.65	---	---
L	0.40	0.50	0.60
aaa	0.10		
bbb	0.10		
ccc	0.05		
ddd	0.05		
eee	0.10		
fff	0.10		


RECOMMENDED LAND PATTERN

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*


XXXX = Specific Device Code

A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TDFN4 8.00x8.00x1.00, 2.00P	PAGE 1 OF 1

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